

EE382M.20: System-on-Chip (SoC) Design

Lecture 14 – Emulation & Prototyping

*Sources:
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Lecture 14: Outline

- **Emulation and prototyping**
 - Design validation
 - Field Programmable Gate Arrays (FPGAs)
- **Programmable Logic Devices**
 - History and types
 - FPGA technology
 - FPGAs for production, emulation & prototyping
- **Prototyping Board**
 - Xilinx Series 7 FPGAs
 - Zynq-7000
 - ZedBoard

Design Validation

- **Verification & validation (debug) account for more than 70% of SoC design effort**
 - (Formal) verification vs. (functional) validation
 - Correctness (wrt specification) vs. performance (wrt purpose/requirements)
 - “Did we build the thing right?” vs. “Did we build the right thing?”
 - Validation of implementation properties requires execution
 - **Complex SoCs are impractical to simulate at the whole-system level**
 - Simulation more tractable at the block level
 - SoCs depend upon complex interactions between SW and among disparate HW elements.
 - Execution of application SW usually required
- **Emulation and prototyping is on the order of 50 to 10,000 time faster than host-based simulation**

Validation Approaches

- **Simulation (aka Virtual Prototyping)**
 - Execute model of design on host machine
 - Co-simulation between different models (e.g. SystemC+HDL)
 - Very good observability & debugability
- **Emulation**
 - Execute model of design in (reconfigurable) hardware
 - Can potentially simulate logical time in hardware-accelerated form
 - Integrate extensive debugging & tracing capabilities
- **(Physical) Prototyping**
 - Synthesize RTL directly into (reconfigurable) hardware
 - Cycle-accurate execution at speed of prototyping hardware
 - Limited observability & debugging

Field Programmable Gate Arrays (FPGAs)

- **Pre-manufactured yet reconfigurable logic**
 - Emulation and prototyping platform for ASIC designs
 - Validation and verification before costly ASIC spin
 - Limits in size and speed
 - In production as system component
 - Flexibility of static or dynamic reconfiguration via download of bitstream
 - Between hardware and software, cost vs. benefit analysis
- **Implement logic via memories**
 - Lookup tables (LUTs)
 - Arbitrary boolean functions as table in memory
 - Configurable Logic Blocks (CLBs)
 - Combine LUTs with flip-flops and latches to realize sequential logic
 - Switch matrices (programmable interconnect)
 - Connect array of CLBs via multiplexers configured by internal registers

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Early Programmable Logic Devices

- **Programmable Read-Only Memory (PROM) devices (1956)**
 - Programmed to realize arbitrary combinational functions
 - Combinational inputs wire to PROM address bits
 - Combinational outputs driven by PROM data bits
- **Mask-programmable gate arrays (MPGA) were introduced by Motorola in 1969**
 - Similar “Programmable Logic Array” (PLA) by TI in 1970
 - Customized during fabrication by the device vendor
 - High non-recurring engineering (NRE) charge and long lead times
- **In 1971, General Electric combined PROM technology with gate array structures**
 - First field programmable logic device
 - Customized by end user
 - Low NRE costs and fast time-to-market
 - Experimental only – never released

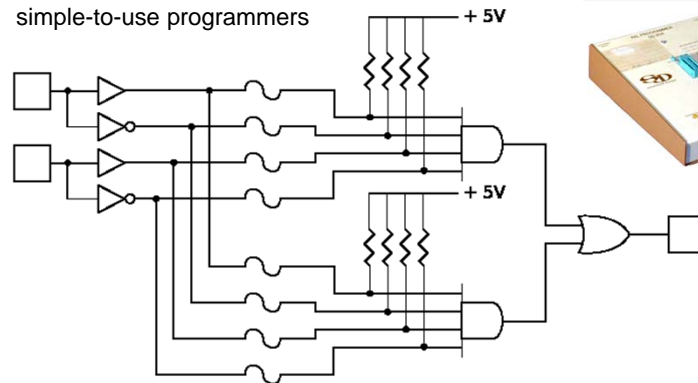
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Programmable Array Logic (PAL)

- **Monolithic Memories Inc. (MMI), based on GE ideas (1978)**
 - Programmable AND and OR planes
 - Each junction in the PAL is a fuse
 - Simpler and faster than earlier PLAs
 - Simple design flow and tools (PALASM)
 - Data I/O introduced low-cost, simple-to-use programmers



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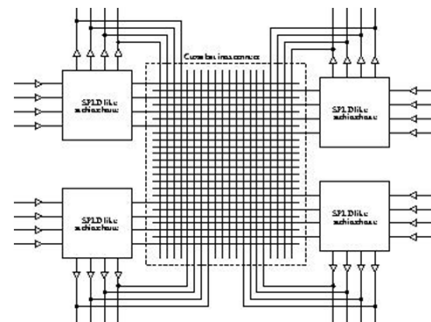
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Field Programmable Logic Devices

- **Altera (formed in 1983), introduced the reprogrammable Electrically Programmable Logic Device (EPLD) in 1984**
- **Lattice Semiconductor introduced Generic Array Logic (GAL) devices in 1985**
 - Basically a reprogrammable PAL
- **Complex Programmable Logic Device (CPLD) technology emerged in the mid 1980s, first released by Altera**
 - A number of Simple PLDs (PAL-like structures + FF)
 - With programmable interconnect
- **Xilinx (founded in 1984), introduced the first Field Programmable Gate Array (FPGA) in 1985, the XC2064**
 - Contained 64 complex logic blocks (CLBs), each with two 3-input look-up tables (LUTs)

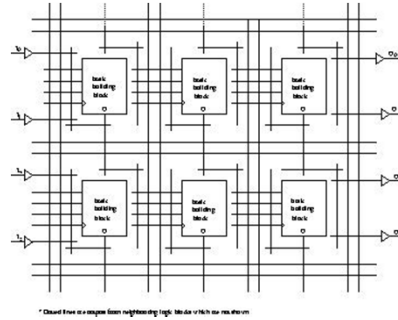
Complex Programmable Logic Device (CPLD)

- **Typically combine coarse-grained SPLD structures with a programmable crossbar interconnect**
 - Don't scale well because of the crossbar interconnect
 - Only limited support for multi-level logic
 - Compared to FPGAs
 - Higher gate density
 - Less interconnect density
 - Better timing uniformity
 - Generally faster in equivalent device technology
- **Non-volatile technology for programming**
 - Memory (reprogrammable)
 - Fuse/anti-fuse (one-time programmable – OTP)



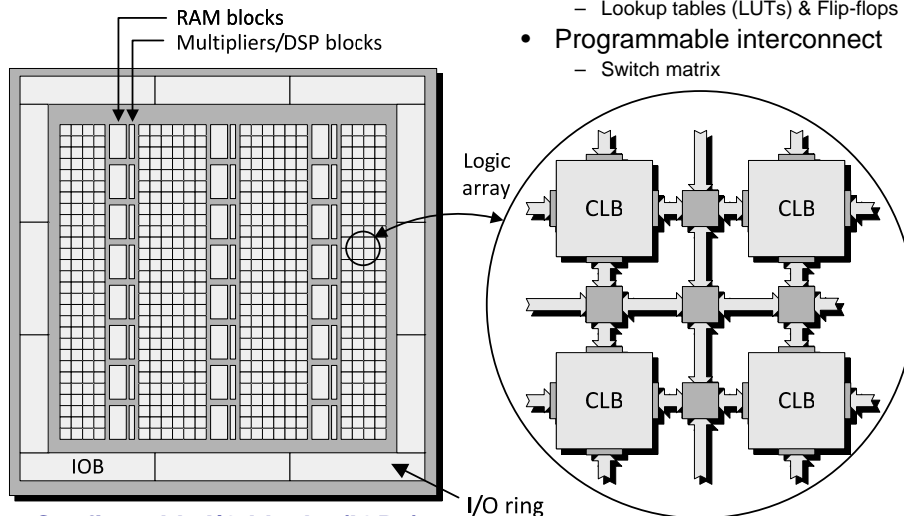
Field Programmable Gate Arrays (FPGAs)

- **Two-dimensional array of customizable logic blocks combined with an interconnect array**
 - Logic blocks based on look-up tables (LUTs) or any other functionally complete behavior
 - Each logic block must offer functional completeness
 - Interconnect based on flexible wire segments
 - Interspersed switches for greater interconnect flexibility than CPLDs
- **Combines the advantages of MPGA and (S)PLD**
 - Comparatively lower gate density with much more complex programmable interconnect capabilities than CPLDs



Modern FPGA Architecture

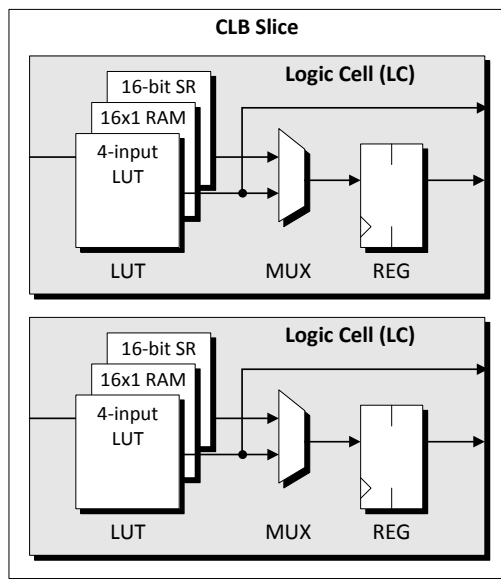
- **Hardcoded logic**
 - Columns of embedded blocks
 - RAM blocks
 - Multipliers/DSP blocks
- **Programmable logic fabric**
 - Configurable logic blocks (CLBs)
 - Lookup tables (LUTs) & Flip-flops (FFs)
 - Programmable interconnect
 - Switch matrix



- **Configurable I/O blocks (IOBs)**

Source: Clive Maxfield, "The Design Warrior's Guide to FPGAs Devices, Tools, and Flows," ISBN 0750676043, © 2004 Mentor Graphics Corp. (mentor.com)

Configurable Logic Blocks (CLBs)



- Each CLB has one or more Slices
- Each Slice has one or more Logic Cells (LCs)
 - 1 Flip-flop (FF) or latch
 - 1 Lookup Table (LUT)
 - Stores truth table for combinational logic
 - Some LUTs can be used as distributed RAM/ROM or shift registers
 - Carry look-ahead (CLA) logic
 - Dedicated muxes

Source: Clive Maxfield, "The Design Warrior's Guide to FPGAs Devices, Tools, and Flows," ISBN 0750676043, © 2004 Mentor Graphics Corp. (mentor.com)
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FPGA Programmability

- **Field programmable capabilities derive from switches**
 - Devices based on fuses (bi-polar) or anti-fuses (CMOS) are one-time programmable (OTP)
 - Devices based on memory are reprogrammable
- **Non-volatile memory-based devices support instant-on functionality (as do OTP devices) and don't require external memory to store device configuration information.**
 - Flash, EPROM, or EEPROM
- **SRAM-based devices offer faster configuration, but require an external non-volatile memory to store configuration information**
 - Requires device "boot"

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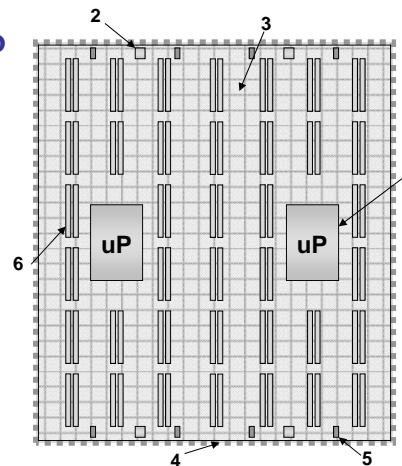
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(Partial) Dynamic Reconfiguration (PDR)

- **Introduced with Xilinx XC6000 in the mid 1990s**
 - Continues to operate while portions are reconfigured
 - Comparatively fine-grained reconfiguration
 - Newer devices, beginning with the Virtex-2 Pro, have more coarse addressability at the bank or slice level
 - Xilinx support for PDR has been sporadic and tentative
 - Repeatedly, announced tool support only to later retract
 - Currently supported and for the first time the tools actually help
- **Altera has not yet developed devices capable of PDR**
 - There are rumors that they may
- **Many interesting applications**
 - Work around size limitations (module swapping)
 - Self-modifying, dynamic instruction set architectures
 - Dynamically instantiate HW accelerators in SoCs

Embedded Processor Cores

- **Pioneered in Xilinx Virtex-II Pro**
 - Up to 4 PowerPC cores
 - Hard macros
 - Throughout Virtex family
 - Virtex 2 through 6
 - Switch to ARM with 7 Series
- **HW/SW co-design**
 - Native SW performance
 - As opposed to emulated soft cores in FPGA fabric



1. PowerPC block
2. RocketIO Multi-Gigabit Transceivers
3. CLB and Configurable Logic
4. SelectIO-Ultra
5. Digital Clock Managers
6. Multipliers and Block SelectRAM

FPGA vs. ASIC for Production Use

- **Much shorter design time**
 - ~Less than a year versus 2-3 years for an ASIC
- **Cost**
 - No NRE vs. \$M development cost for an ASIC
 - Much higher unit costs than those for ASICs
 - Depends on anticipated volume: $NRE + (RE * Volume)$
- **Performance gap**
 - Power consumption: ~7 times dynamic power*
 - Area consumption: ~18 times the area*
- **IP Protection**
 - Exposure during fabrication vs. in the field
- **FPGAs are the fastest growing semiconductor segment**
 - From 10% to approximately 25% in recent years
 - Dramatic decline in ASIC design starts: 11,000->1,500, '97-'02

* Kuon, I.; Rose, J. (2006). Measuring the gap between FPGAs and ASICs. Intl. Symposium on FPGAs, 2006.

FPGAs for Emulation & Prototyping

- **Unmatched execution performance**
- **Cost effective, especially if FPGA evaluation boards are used as an ad hoc emulator**
 - Commercial system can be quite expensive, but are still cheaper than an extra ASIC spin
- **Robust verification possible**
 - Application software may be used in verification process, where it is typically impractical for simulation
- **Reduces design risk for ASICs**
 - Facilitates the fastest path to the market for complex SoC design

Emulation & Prototyping Challenges (1)

- **Size restrictions require partitioning**
 - Most “interesting” designs will require multiple FPGAs
 - Quality of partitioning determines emulation performance
 - Tool support is vendor-specific and not always particularly effective
 - Often the difference between 10 MHz and 400 MHz system clock rates
 - Manual intervention often necessary, costly and time consuming
 - Interface signals among FPGAs may be insufficient for optimal partitions
- **HDL targeting ASIC doesn't always map easily into FPGAs**
 - Clock and initialization logic
 - Memory technology and I/O interfaces may differ
 - E.g., implementation uses flash but emulation only has DRAM
 - Bus models and their implementation may differ
 - Generally no tri-state signals internal to FPGAs
 - Debug, controllability and visibility additions
 - Develop HDL with both FPGA and ASIC in mind

Emulation & Prototyping Challenges (2)

- **Co-verification / co-emulation**
 - Third-party IP may not be available in suitable (HDL) form
 - Interface FPGAs to simulator or C/C++ model running on a general-purpose host
 - Always ends up being gating factor on performance, severely constraining achievable emulation speeds
 - Discrete HW instantiation of third-party IP may require custom interface and models
 - Differences in software processor architectures
 - e.g., FPGA's internal PowerPC hard core instead of target ARM
- **Emulation speed may be limited by I/O bottlenecks**
 - Data collection, Stimuli
- **Partitioning and bit stream generation is time consuming**
 - Recompile may take hours (or worse)

Emulation & Prototyping Challenges (3)

- **In-circuit / in-environment emulation**
 - Interaction with the environment or with other systems
 - If emulated speed is less than the target operational speed, need to consider the impact on real-time operation
 - Network interfaces can often be scaled to retain effective equivalence with real-time operation
 - E.g., Use 10 Mbps Ethernet on emulator running at 1/10 the rate of the target operational speed which is intended to work with 100 Mbps networks
- **In the end, executing an approximate model of target SoC**
 - Important to bear this fact in mind when interpreting results
 - Still need to do extensive verification through simulation of those blocks known to be different between the emulated system and the target design.
 - Same is true for interfaces between blocks and clock and reset logic.

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Major FPGA Device Vendors

- **Xilinx and Altera are market leaders in SRAM-based FPGAs**
 - Combined controlling >80% of FPGA and CPLD market
 - Xilinx ~50%, Altera ~35%
 - Also offer non-volatile and OTP devices
- **Actel (Microsemi) offers anti-fuse and flash-based devices**
 - Igloo and Igloo Nano devices have very low power and sophisticated sleep mode options
 - Finally a programmable logic solution suitable for battery-powered applications
- **Lattice Semiconductors offers SRAM-based devices with integrated configuration flash**

Major FPGA Device Families

- **Xilinx**

Technology	Low-end	Mid-range	High-Performance
120/150 nm			Virtex-II
90 nm	Spartan 3		Virtex-4
65 nm			Virtex-5
40/45 nm	Spartan 6		Virtex-6
28 nm	Artix-7	Kintex-7	Virtex-7
20/16 nm		Kintex UltraScale	Virtex UltraScale

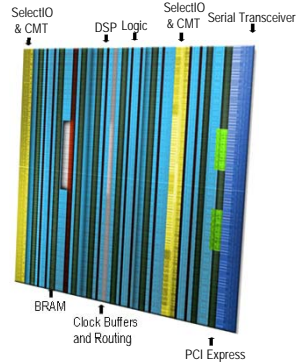
- **Altera**

Technology	Low-end	Mid-range	High-Performance
130 nm	Cyclone		Stratix
90 nm	Cyclone II		Stratix II
65 nm	Cyclone III	Arria I	Stratix III
40 nm	Cyclone IV	Arria II	Stratix IV
28 nm	Cyclone V	Arria V	Stratix V
20/14 nm		Arria 10	Stratix 10

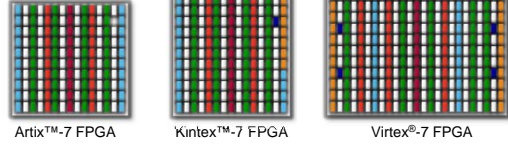
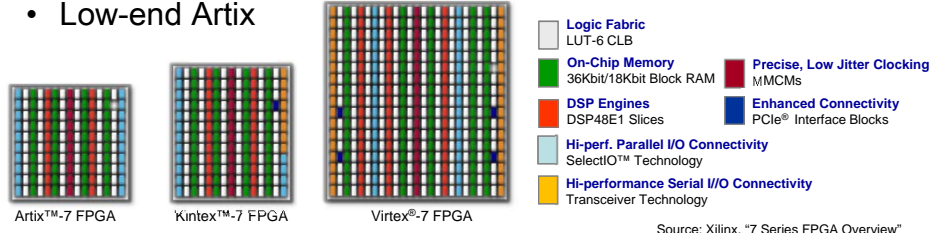
Xilinx 7 Series

- Unified architecture (28 nm, 1.0V)**

- Scalable column-based architecture
 - Using common building blocks
 - » CLBs, DSPs, IOBs, Tranceivers, PCIe, ADCs, Clock management tiles (CMTs)
 - Low-power features
- High-end Virtex family
 - 3D multi-die stacked silicon interconnect (SSI)
 - up to 8 Mbytes RAM
 - up to 1200 user I/O pins
 - up to 2M logic cells & 2.4M FFs



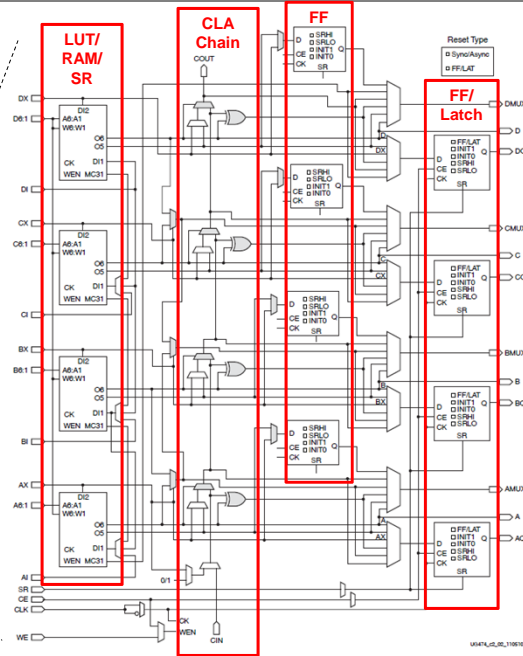
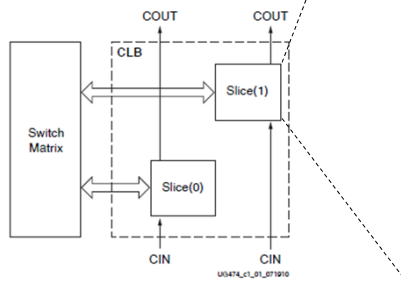
- Mid-range Kintex
- Low-end Artix



Xilinx 7 Series CLBs

- 2 slices per CLB**

- 6-input LUT
 - RAM/SR in SLICEM
 - Logic only in SLICEL
- 4 FF/Ls
- 4 FFs
 - Only if all FFs
- Carry chain
- Wide muxes

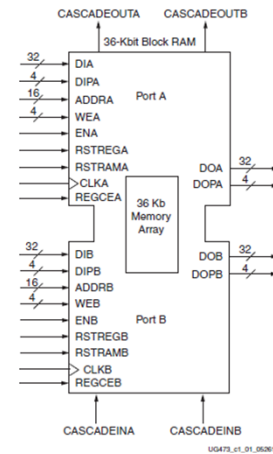


Source: Xilinx, "7 Series FPGA Configurable Logic Block User Guide"

Xilinx 7 Series Block RAMs

- **36kB (or 2x 18kB) block RAMs (BRAMs)**

- Synchronous RAM
- Dual-ported (no contention avoidance!)
 - 36kB: 32Kx1, 16Kx2, 8Kx4, 4Kx9, 2Kx18, 1Kx36
 - 18kB: 16Kx1, 8Kx2, 4Kx4, 2Kx9, 1Kx18
- Single-port mode (“Simple Dual-Port”)
 - 512x36 (18kB) or 512x72 (36kB)
- Can be cascaded
 - Two adjacent BRAMs cascadable to 64Kx1 without any logic overhead
- Built-in error correction
 - 64-bit ECC (correct single, detect two bit)
- FIFO mode



Source: Xilinx, "7 Series FPGA Memory Resources User Guide"

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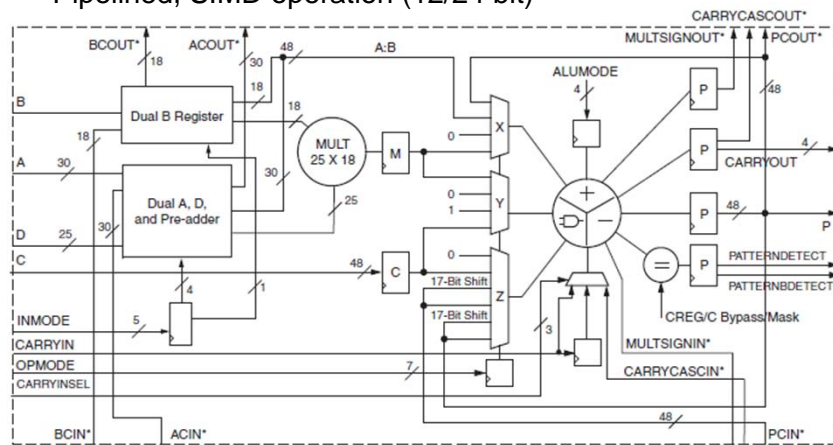
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Xilinx 7 Series DSP48E1 Slices

- **Support 96-bit Multiply-Accumulate (MACC) operation**

- 25-bit pre-adder, 25x18 signed multiplier, 48-bit ALU
 - Plus 17-bit shifter, pattern detector
 - Cascade paths for wide functions
- Pipelined, SIMD operation (12/24 bit)



*These signals are dedicated routing paths internal to the DSP48E1 column. They are not accessible via fabric routing resources.

Source: Xilinx, "7 Series FPGA DSP48E1 Slice User Guide"

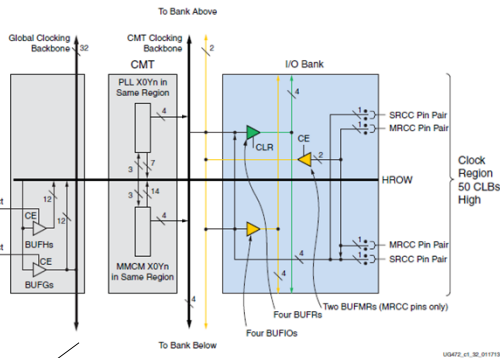
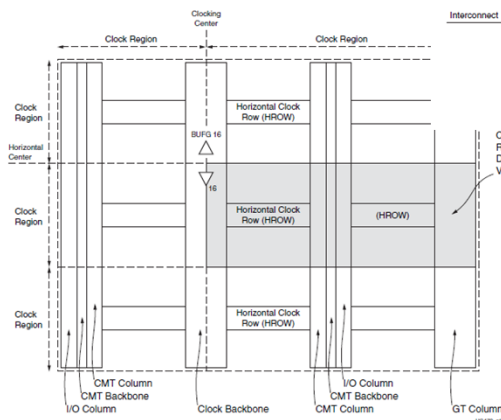
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Xilinx 7 Series Clocking

- **Divide into clock regions**
 - $\frac{1}{2}$ width x 50 CLBs each
 - 10 BRAMs, 20 DSPs high
 - 50 IOBs, 4 T/x, PCIe
 - Buffers/repeaters



- **Clock management tiles (CMTs)**

- Adjacent to I/O columns
 - 1 per region, 2 columns/device
- Center clock spine
 - 1 horizontal clock row/region

Source: Xilinx, "7 Series FPGA Clocking Resources User Guide"

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Xilinx 7 Series I/O

- **SelectIO Input/Output Blocks (IOBs)**
 - 2 columns per device, 50 IOBs per bank
 - Two distinct IOB types
 - High range: supports standards up to 3.3V
 - High performance: supports I/O standards up to 1.8V
- **High-Speed Serial I/O Transceivers**
 - Transceivers in quads, 4 per block
 - Different types, multiple standards
 - GTP/GTX/GTH/GTZ (3.75/12.5/13.1/28 Gbps)
- **PCI Express (PCIe) Blocks**
 - Build on GTX serial I/O transceivers
 - Compliant to PCIe protocol Gen1/Gen2/Gen3 (2.5/5/8 Gbps)
- **Analog-to-Digital Converter Blocks (XADCs)**
 - Two 12-bit, 1 Msps ADCs plus on-chip sensors per XADC

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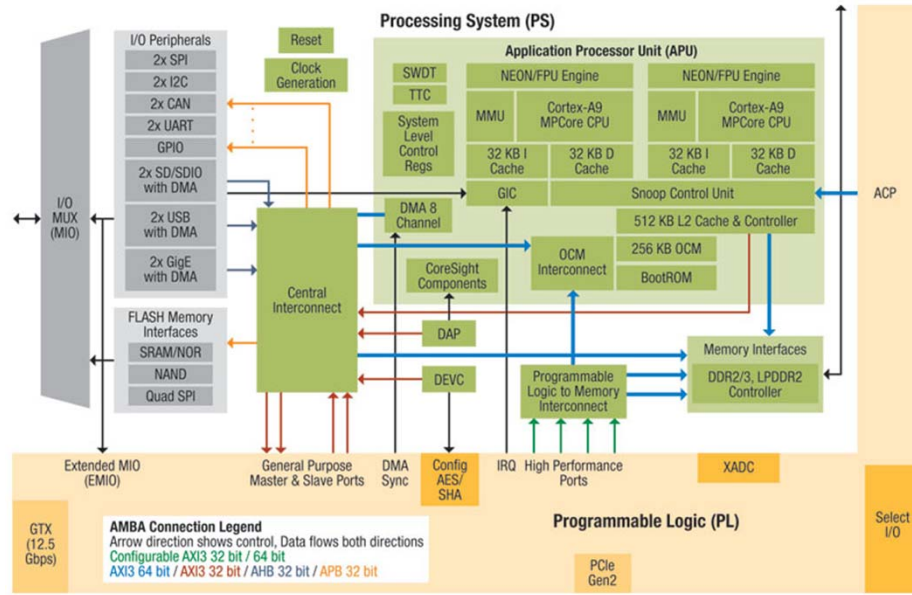
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Xilinx Zynq-7000

- **Extensible Processing Platform (EPP) / All-Programmable (AP) SoC**
 - FPGA fabric with embedded ARM processor on single die
 - Programmable logic (PL)
 - Processing system (PS)
 - PL based on Xilinx Series 7 FPGA technology
 - Artix-7 or Kintex-7 fabric (28nm TSMC HPL process)
 - Multi-standard I/O, gigabit transceivers, analog-to-digital converters (ADCs)
 - PS based on dual-core Cortex-A9
 - ARM Cortex-A9 MPCore (ARMv7 ISA, up to 1GHz)
 - L1/L2 caches, on-chip SRAM, ext. DRAM interfaces, peripherals
- **SoC prototyping platform**
 - Industry-standard ecosystems
 - Tool support (Xilinx/HLS +ARM/Linux)



Zynq-7000 Block Diagram



Source: G. Brown/Xilinx, "Designing ASP-Type Devices: What Does it Take?," RTC Magazine, March 2012

Zynq-7000 Processing System (PS)

• Application Processing Unit (APU)

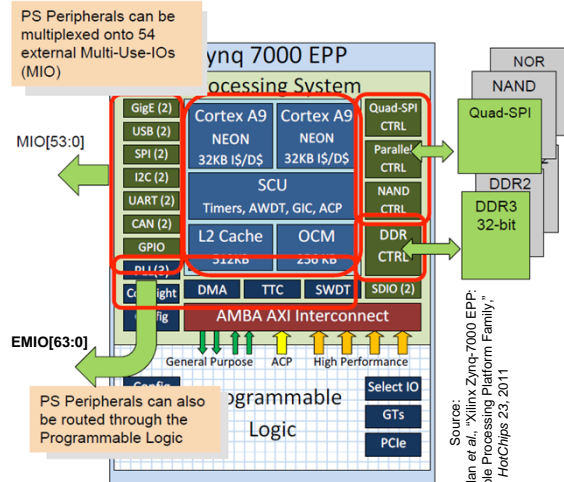
- Dual-core Cortex-A9
 - NEON SIMD/FP unit
 - 512kB L2 cache
- Snoop Control Unit (SCU)
 - L1 cache coherency
- On-Chip Memory (OCM)
 - Dual-ported 256kB SRAM

• External memory interfaces

- DDR3/DDR2
 - ECC memory controller
- Config & legacy
 - Quad-SPI, NAND/NOR flash

• Peripherals

- Standard I/O for PS or PL
 - GPIO, 2x USB, 2x CAN, 2x I2C, 2x UART, 2x Ethernet, 2x SPI
- System peripherals controlled by/local to PS
 - Clock (PLL), debug access port (DAP), DMA ctrl., interrupt ctrl. (GIC), timers

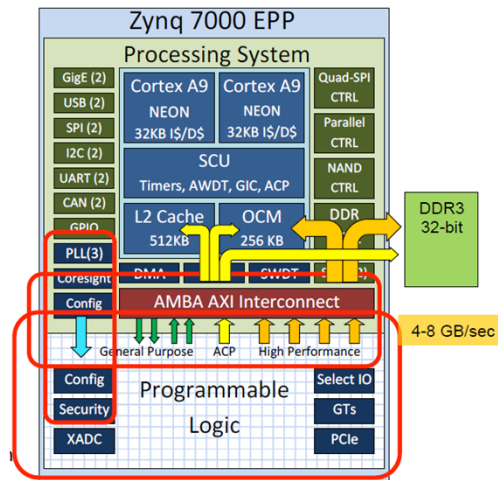


Source: V. Rajagopalan et al., "Xilinx Zynq-7000 EPP: An Extensible Processing Platform Family," HerChips 23, 2011

Zynq-7000 Programmable Logic (PL)

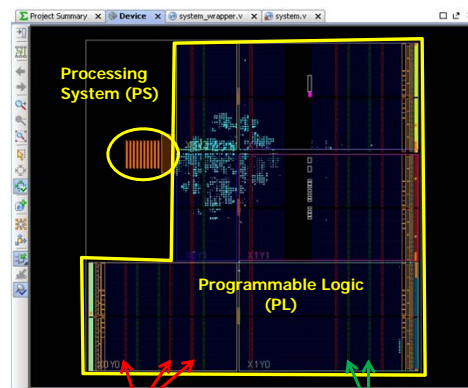
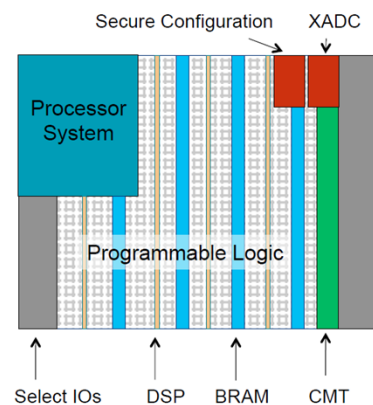
• PL-PS Interfaces

- Accelerator Coherence Port (ACP)
 - Coherent access to caches
- General-purpose (GP) AXI ports
 - 2x master, 2x slave
 - Connect to central crossbar
- High-performance (HP) AXI ports
 - 4x master, FIFO buffered
 - Direct memory access (DMA)
- System interfaces
 - 16 shared interrupts to GIC, 4 private interrupts to cores (2x nIRQ/nFIQ)
 - Debug



Source: V. Rajagopalan et al., "Xilinx Zynq-7000 EPP: An Extensible Processing Platform Family," *HotChips* 23, 2011

Zynq-7000 Logic Fabric



Block RAMs in red DSP blocks in green

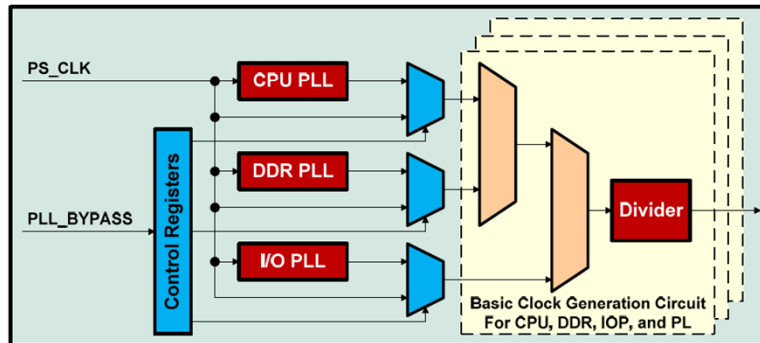
• Xilinx Series-7 FPGA fabric

- Embedded block RAM (BRAM) & DSP slices
- Clock management tiles (CMT), I/O
- PCI-Express & A/D interfaces

Source: V. Rajagopalan et al., "Xilinx Zynq-7000 EPP: An Extensible Processing Platform Family," *HotChips* 23, 2011

Zynq-7000 Clocks

- **Clock generation module**
 - Generate clocks for CPU, DDR, I/O and PL
 - Phase-locked loops (PLLs)
 - PS_CLK is external 30-60 MHz reference clock
 - Four general-purpose clocks for PL
 - FCLK_CLK0, FCLK_CLK1, FCLK_CLK2, FCLK_CLK3



Source: Avnet Inc., "Introduction to the Xilinx Zynq-7000 EPP," Avnet Xfest, 2012

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Zynq-7000 Memory Map

- **4GB of addressable memory**

Address Range	CPUs and ACP	AXI_HP	Other Bus Masters ⁽¹⁾	Notes
0000_0000 to 0003_FFFF ⁽²⁾	OCM	OCM	OCM	Address not filtered by SCU and OCM is mapped low
	DDR	OCM	OCM	Address filtered by SCU and OCM is mapped low
	DDR			Address filtered by SCU and OCM is not mapped low
0004_0000 to 0007_FFFF	DDR			Address not filtered by SCU and OCM is not mapped low
				Address filtered by SCU
0008_0000 to 000F_FFFF	DDR	DDR	DDR	Address not filtered by SCU
0010_0000 to 3FFF_FFFF	DDR	DDR	DDR	Address filtered by SCU
	DDR	DDR	DDR	Address not filtered by SCU ⁽³⁾
0010_0000 to 3FFF_FFFF	DDR	DDR	DDR	Accessible to all interconnect masters
4000_0000 to 7FFF_FFFF	PL		PL	General Purpose Port #0 to the PL, M_AXI_GP0
8000_0000 to BFFF_FFFF	PL		PL	General Purpose Port #1 to the PL, M_AXI_GP1
E000_0000 to E02F_FFFF	IOP		IOP	I/O Peripheral registers, see Table 4-6
E100_0000 to ESFF_FFFF	SMC		SMC	SMC Memories, see Table 4-5
F800_0000 to F800_0BFF	SLCR		SLCR	SLCR registers, see Table 4-3
F800_1000 to F880_FFFF	PS		PS	PS System registers, see Table 4-7
F890_0000 to F8F0_2FFF	CPU			CPU Private registers, see Table 4-4
FC00_0000 to FDFE_FFFF ⁽⁴⁾	Quad-SPI		Quad-SPI	Quad-SPI linear address for linear mode
FFFC_0000 to FFFF_FFFF ⁽²⁾	OCM	OCM	OCM	OCM is mapped high
				OCM is not mapped high

Source: Xilinx, "Zynq-7000 Technical Reference Manual (TRM)"

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Zynq-7000 Device Family

- Currently 7 different Z-devices
 - Low-end (7010, 7015, 7020), mid-range (7030, 7035, 7045, 7100)
 - Different packaging options (I/O)
 - Different speed grades (max. frequency)

	Z-7010	Z-7015	Z-7020	Z-7030	Z-7045	Z-7100	
Processing System	Processor Core	Dual ARM® Cortex™-A9 MPCore™ with CoreSight™					
	Processor Extensions	NEON™ & Single / Double Precision Floating Point for each processor					
	Cache	L1: 32kB Instruction/32kB Data per processor, L2: 512kB shared					
	On-Chip Memory	256 KB					
	Memory Interfaces	DDR3, DDR3L, DDR2, LPDDR2, 2x Quad-SPI, NAND, NOR					
	Peripherals	2x USB 2.0 (OTG), 2x Tri-mode Gigabit Ethernet, 2x SD/SDIO					
Programmable Logic	Programmable Logic	Artix-7	Artix-7	Artix-7	Kintex-7	Kintex-7	Kintex-7
	Logic Cells (Gate equiv.)	28K Cells (~430k)	74K Cells (~1.1M)	85K Cells (~1.3M)	125K Cells (~1.9M)	350K Cells (~5.2M)	444K Cells (~6.6M)
	Block RAMs @ 36kB	60 (240kB)	95 (380kB)	140 (560kB)	265 (1,060kB)	545 (2,180kB)	755 (3,020kB)
	DSP Slices	80	160	220	400	900	2,020
	PCI Express	-	Gen2 x4	-	Gen2 x4	Gen2 x8	Gen2 x8
Analog/Mixed-Signal	2x 12-bit, 1Ms/s ADCs with up to 17 differential inputs						
I/O	Processor System	up to 130					
	High-Range 3.3V	up to 100	up to 150	up to 200	up to 100	up to 250	up to 250
	High-Performance 1.8V	-	-	-	up to 150	up to 150	up to 150
	Gigabit Transceivers	-	4 (6.25 Gb/s)	-	up to 4 (12.5 Gb/s)	up to 16 (12.5Gb/s)	up to 16 (10.3Gb/s)

Source: Xilinx, "Zynq-7000 All Programmable SoC Overview"

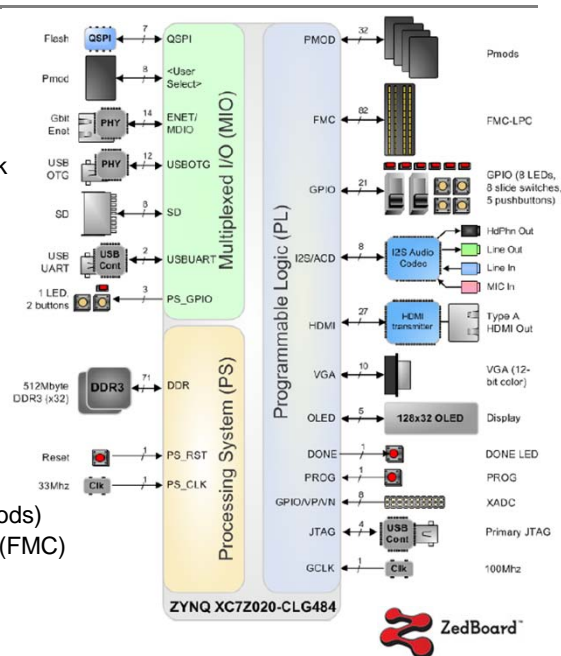
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ZedBoard

- Zynq-7000 based prototyping board
 - Z-7020, -1 grade
 - 667MHz max. ARM clock
 - 150 MHz bus clock
 - On-board DRAM
 - 512MB DDR3
 - MIO interfaces
 - LED & switch GPIO
 - Ethernet, USB, UART
 - SD card
 - PL peripherals
 - Audio, video, display
 - Peripheral modules (Pmods)
 - FPGA mezzanine cards (FMC)
 - System control
 - Reset, clock, debug

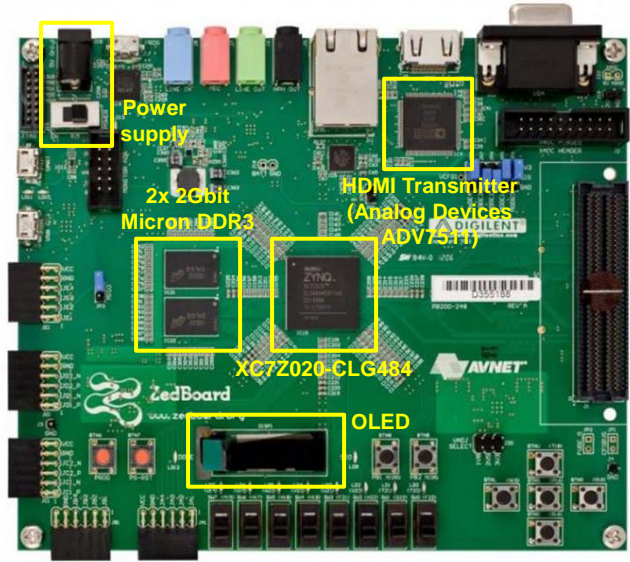


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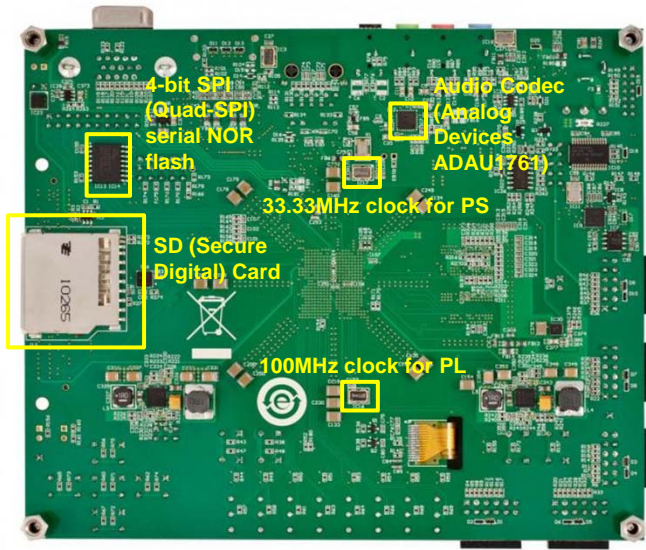
40

ZedBoard (Front)



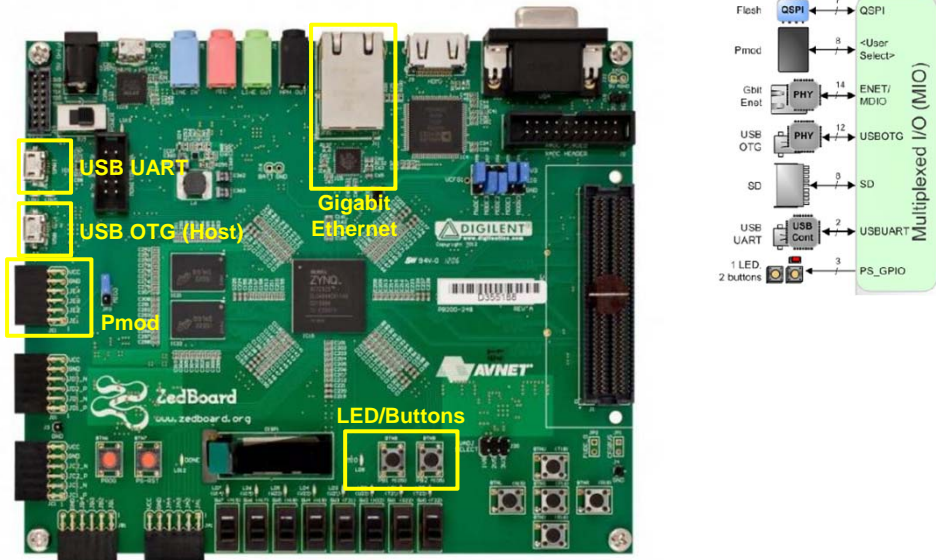
Source: Taeweon Suh, Korea University

ZedBoard (Back)

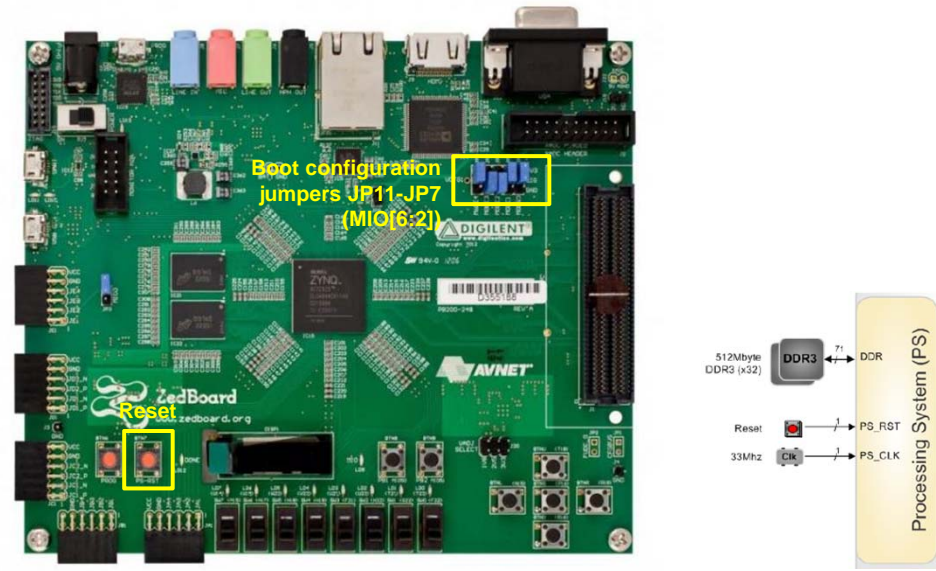


Source: Taeweon Suh, Korea University

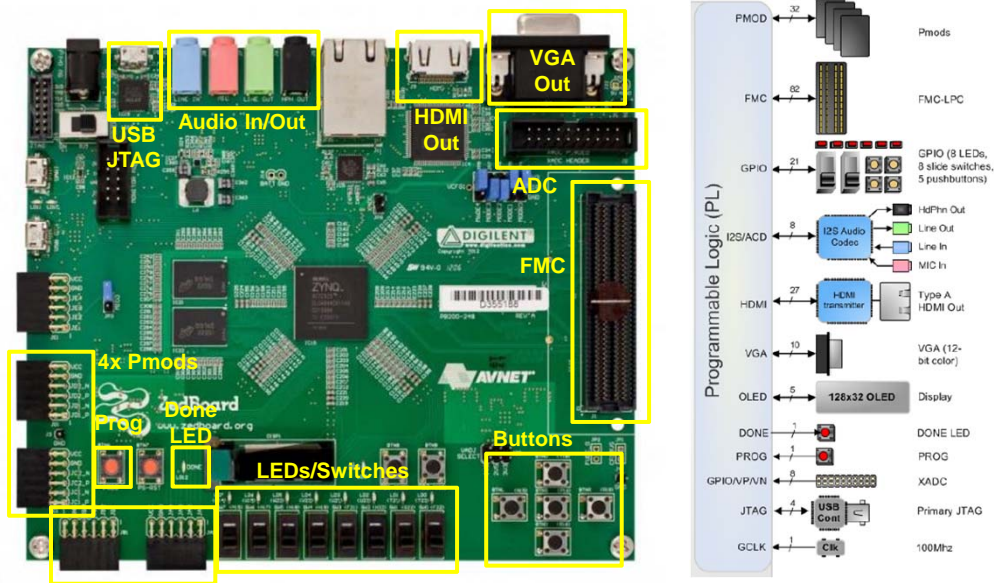
ZedBoard Multiplexed I/O (MIO)



ZedBoard PS I/O



ZedBoard PL I/O



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More Zynq/ZedBoard Information

- Zynq-7000 Technical Reference Manual (TRM)**
http://www.xilinx.com/support/documentation/user_guides/ug585-Zynq-7000-TRM.pdf
- Xilinx presentations**
<http://www.xilinx.com/innovation/research-labs/conferences/hotchips23-wittig.pdf>
http://tcfpga.org/fpga2013/VivadoHLS_Tutorial.pdf
- COM509, "Computer Systems", Korea University**
http://esca.korea.ac.kr/teaching/com509_CS/
- Avnet® X-fest 2012 presentations**
http://www.em.avnet.com/en-us/design/trainingandevents/Documents/X-FEST%202012%20PRESENTATIONS/xfest12_pdf_zedboard_v1_2_may15.pdf
http://www.em.avnet.com/en-us/design/trainingandevents/Documents/X-FEST%202012%20PRESENTATIONS/xfest12_pdf_zynq_intro_v1_1_april29.pdf
- Xilinx 7 Series FPGA tutorials**
https://arco.esi.uclm.es/public/doc/tutoriales/Xilinx/FPGA_Architecture/7-Series/

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Lecture 14: Summary

- **Programmable logic devices emerged in the 1970s and have advanced steadily since**
 - CPLDs and FPGAs have fundamentally different structures and, typically, different applications.
 - The emergence of very low-power devices has opened up potential applications in battery-powered applications, previously a complete non-starter
- **FPGAs are the fastest growing segment of the semiconductor market.**
 - All but very high volume consumer applications are likely better served by FPGAs than ASICs.
- **Emulation and prototyping offers an effective and powerful means of reducing design risks, development time and costs for ASIC designs**